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Silicon Carbide and Other Wide Bandgap Materials: Fundamentals, Device Applications and Future Prospects

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Message from the Guest Editor

Dear Colleagues,

SiC, being one of the most widely used wide bandgap materials, plays a critical role in power industries by setting new standards in power savings as switches or rectifiers in the system for electric vehicles, wind turbines, solar cells, data centers, as well as high temperature and radiation tolerant electronic applications.

This Special Issue is focused on recent progress in all topics related to SiC materials and devices. Topics of interest in the issue include (but are not limited to):

- Bulk and Epitaxial Growth of SiC
- Heterostructures or related materials (graphene, GaN, Ga₂O₃, ZnO, etc.) grown on SiC
- Defect Analysis and Engineering
- Device Design and Fabrication Processes in SiC
- Packaging, Applications and Reliability for Power Electronics
- Novel devices



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Special Issue



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Message from the Editor-in-Chief

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